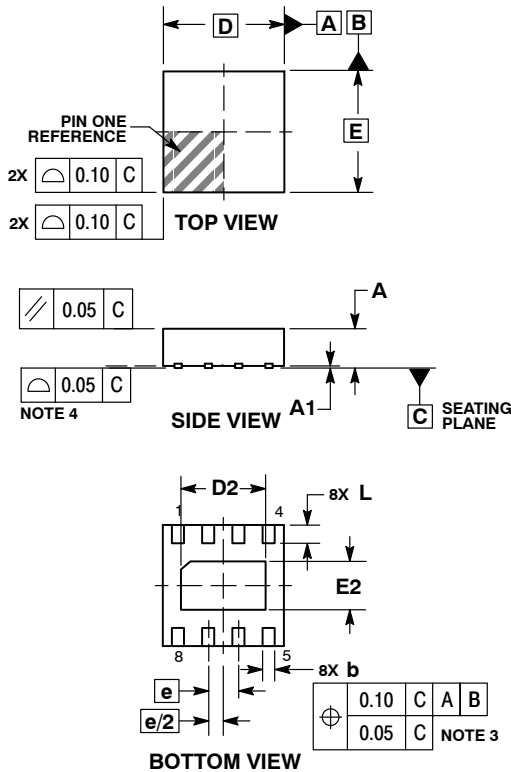**onsemi**™

CUDFN8, 2x2, 0.5P
CASE 505AP
ISSUE O

SCALE 2:1
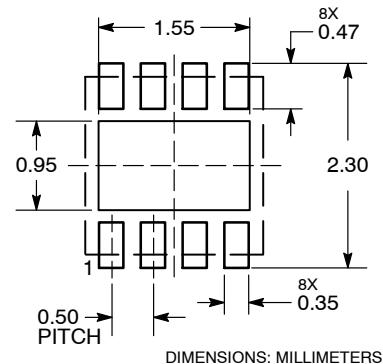
DATE 19 DEC 2016

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.55	0.65
A1	0.00	0.05
b	0.20	0.30
D	2.00 BSC	
D2	1.30	1.50
E	2.00 BSC	
E2	0.70	0.90
e	0.50 BSC	
L	0.25	0.35

TOP VIEW

PIN ONE REFERENCE

2X ⌒ 0.10 C
2X ⌒ 0.10 C

∥ 0.05 C
⌒ 0.05 C
NOTE 4

SIDE VIEW

A
A1
C SEATING PLANE

BOTTOM VIEW

D2
8X L
E2
8X b
e
e/2

⊕ 0.10 C A B
0.05 C NOTE 3

GENERIC MARKING DIAGRAM*

(*Note: Clear package, no marking is present)

RECOMMENDED MOUNTING FOOTPRINT*

1.55
8X 0.47
0.95
2.30
8X 0.35
0.50 PITCH

DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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